

N-Channel Super Junction Power MOSFET IV

General Description

The series of devices use advanced trench gate super junction technology and design to provide ultra-low $R_{DS(ON)}$ and low gate charge and With a rapid recovery body diode. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, industrial power applications, Fast charger, new energy vehicle charging pile, on-board OBC etc.

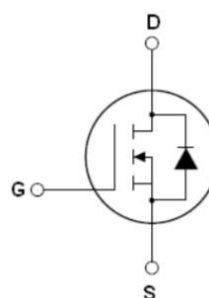
Features

- New technology for high voltage device
- Ultra low on-resistance and ultra low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- Diode reverse recovery speed is super fast
- 100% Avalanche Tested and 100% T_{rr} Tested
- High reliability
- RoHS&Halogen Free

Application

- Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible Power Supply (UPS)
- On-board charger (OBC)

$V_{DS \min @ T_{jmax}}$	710	V
$R_{DS(ON) TYP.}$	30	m Ω
I_D	70	A
Q_g	125	nC



✧ **Intrinsic fast-recovery body diode**

Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65NF036T4	TO-247-4L	NCE65NF036T4



TO-247-4L

Table 1. Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS}=0V$)	V_{DS}	650	V
Gate-Source Voltage ($V_{DS}=0V$), AC ($f>1\text{ Hz}$)	V_{GS}	± 30	V
Gate-Source Voltage ($V_{DS}=0V$), DC	V_{GS}	± 20	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_{D(DC)}$	70	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_{D(DC)}$	49	A
Pulsed drain current (Note 1)	$I_{DM}(\text{pluse})$	210	A
Maximum Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	488	W
Derate above 25°C		3.25	W/ $^\circ\text{C}$
Single pulse avalanche energy (Note 2)	E_{AS}	784	mJ
Single pulse avalanche current (Note 2)	I_{AS}	14	A
Repetitive Avalanche energy, t_{AR} limited by T_{jmax} (Note 1)	E_{AR}	0.8	mJ

Reverse diode dv/dt, $V_{DS} \leq 480V, I_{SD} < I_D$	dv/dt	50	V/ns
Drain Source voltage slope, $V_{DS} \leq 480V$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55...+175	°C

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R_{thJC}	0.31	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R_{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =1mA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V, V _{GS} =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V, V _{GS} =0V			600	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±200	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =3mA	3.5	4.2	5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =35A		30	36	mΩ
Dynamic Characteristics						
Gate Resistance	R _g	F=1MHZ, D-S short		4		Ω
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V, F=1MHZ		7727		pF
Output Capacitance	C _{oss}			263		pF
Reverse Transfer Capacitance	C _{rss}			25.1		pF
Total Gate Charge	Q _g	V _{DS} =400V, I _D =40A, V _{GS} =10V		125	135	nC
Gate-Source Charge	Q _{gs}			57		nC
Gate-Drain Charge	Q _{gd}			34		nC
Gate plateau voltage	V _{gp}			6.5		V
Switching times						
Turn-on Delay Time	t _{d(on)}	V _{DD} =380V, I _D =40A, R _G =4Ω, V _{GS} =10V		54		nS
Turn-on Rise Time	t _r			37		nS
Turn-Off Delay Time	t _{d(off)}			127		nS
Turn-Off Fall Time	t _f			5		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T _C =25℃			70	A
Pulsed-Source-drain current(Body Diode)	I _{SDM}				210	A
Forward on voltage	V _{SD}	T _j =25℃, I _{SD} =70A, V _{GS} =0V		1.0	1.2	V
Reverse Recovery Time	t _{rr}	T _j =25℃, I _F 40A, di/dt=100A/μs		185		nS
Reverse Recovery Charge	Q _{rr}			1.6		uC
Peak reverse recovery current	I _{rrm}			16		A

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. $T_J=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

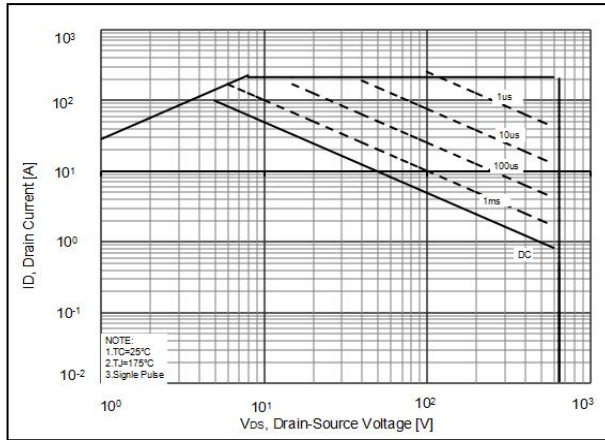


Figure2. Source-Drain Diode Forward Voltage

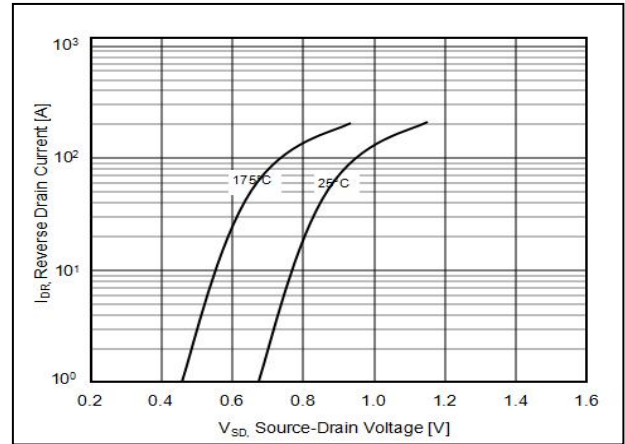


Figure3. Output characteristics (25°C)

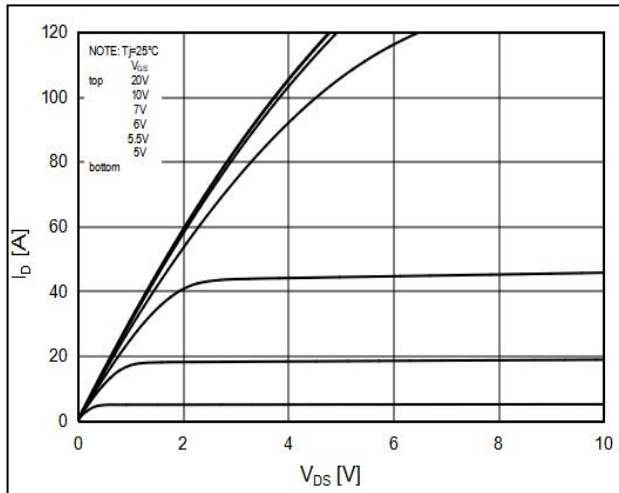


Figure4. Transfer characteristics

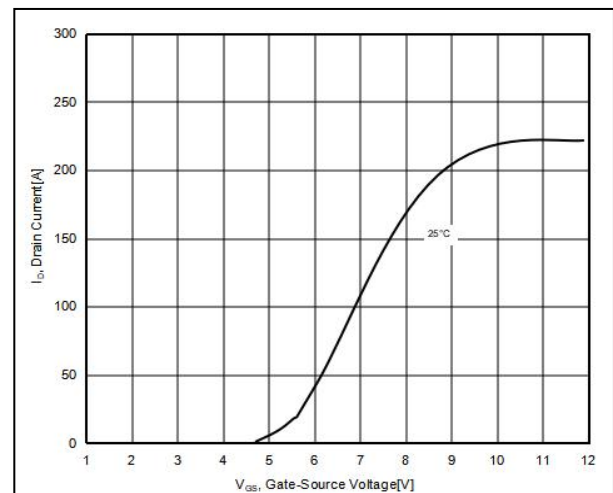


Figure5. Static drain-source on resistance

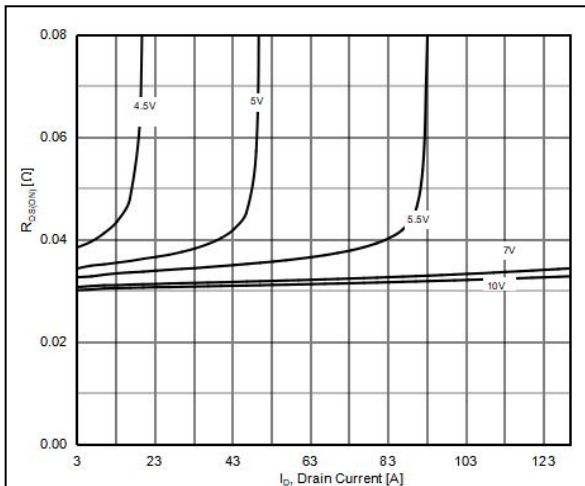


Figure6. RDS(ON) vs Junction Temperature

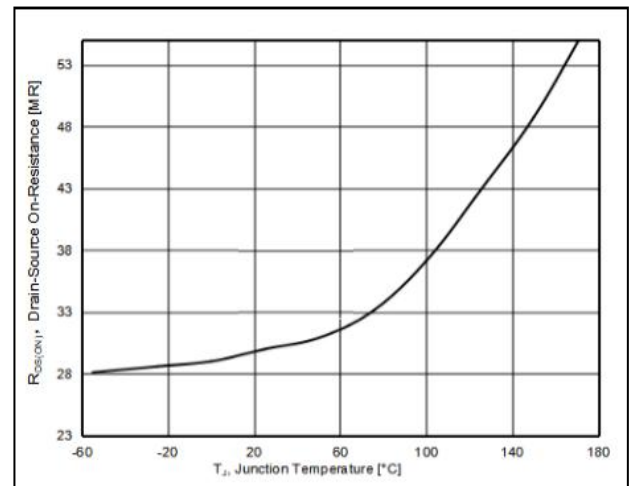


Figure7. BV_{DSS} vs Junction Temperature

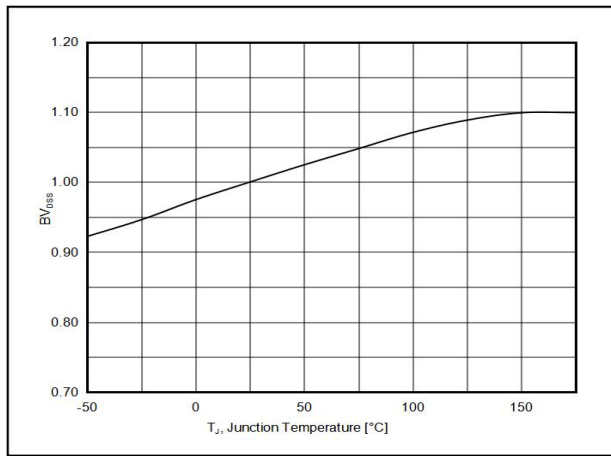


Figure8. Maximum I_D vs Junction Temperature

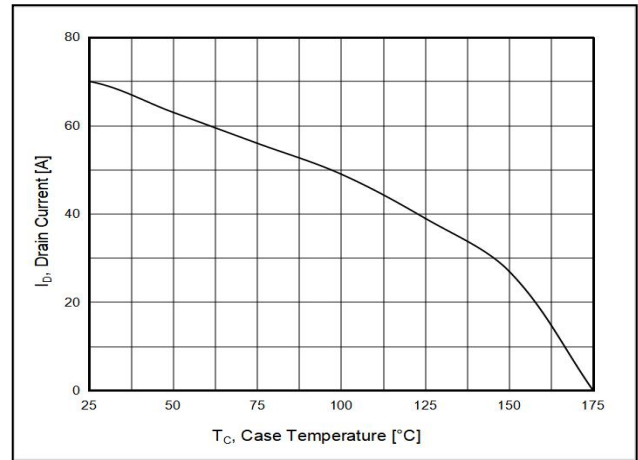


Figure9. Gate charge waveforms

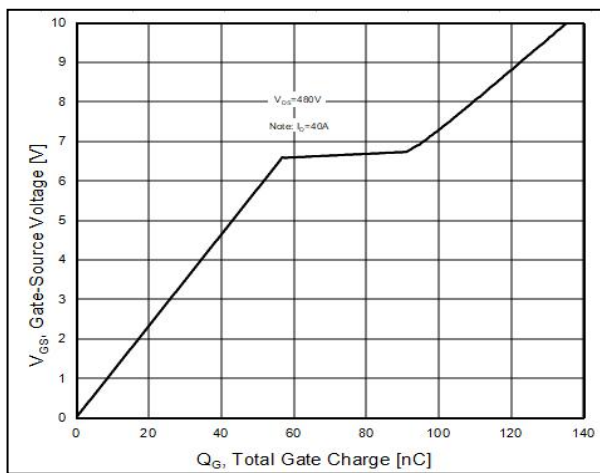


Figure10. Capacitance

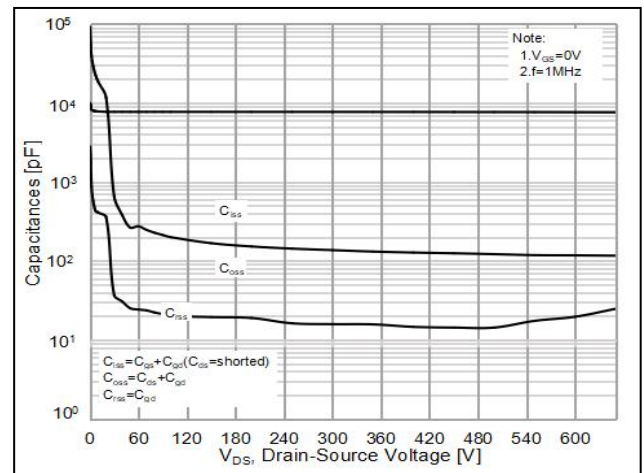
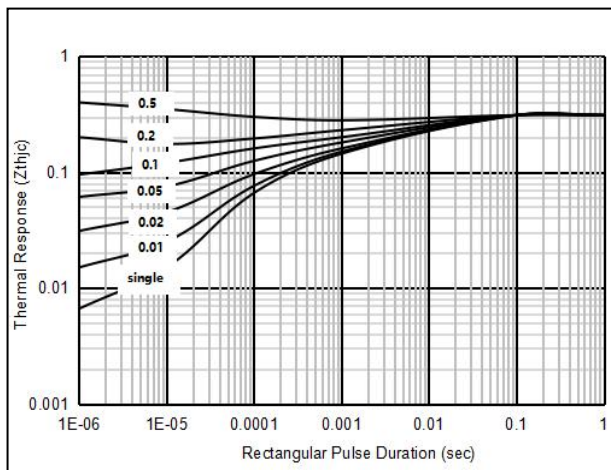
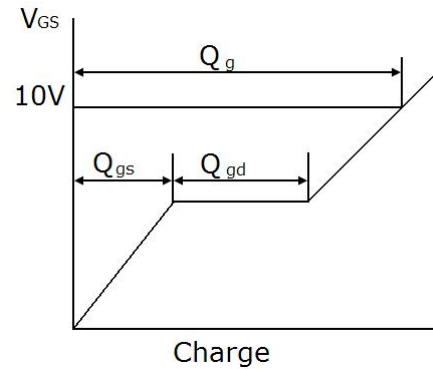


Figure11. Transient Thermal Impedance

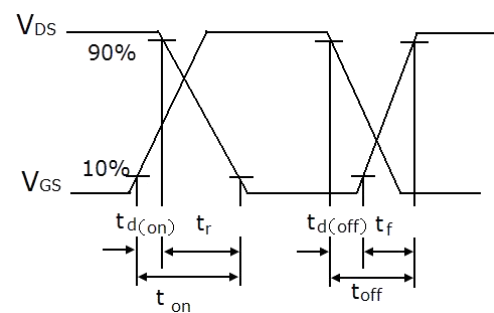
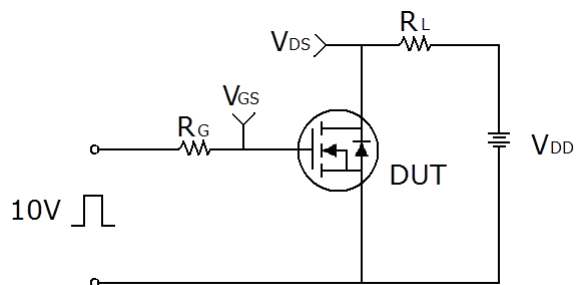


Test circuit

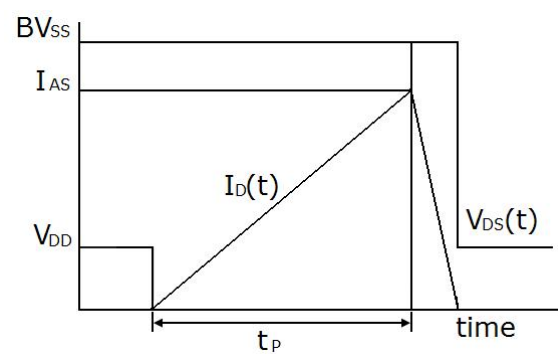
1) Gate charge test circuit & Waveform



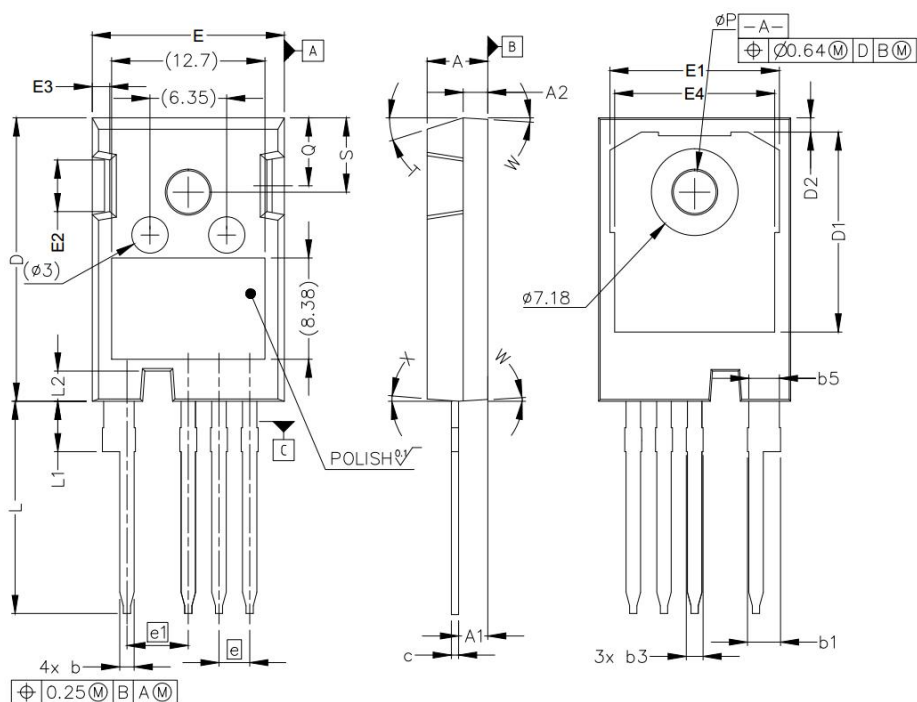
2) Switch Time Test Circuit:



3) Unclamped Inductive Switching Test Circuit & Waveforms



TO-247-4L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.83	5.21	0.19	0.21
A1	2.29	2.54	0.09	0.10
A2	1.91	2.16	0.08	0.09
b	1.07	1.33	0.04	0.05
b1	2.39	2.94	0.09	0.12
b3	1.07	1.60	0.04	0.06
b5	2.39	2.69	0.09	0.11
c	0.55	0.68	0.02	0.03
D	23.30	23.60	0.92	0.93
D1	16.25	17.65	0.64	0.69
D2	0.95	1.25	0.04	0.05
E	15.75	16.13	0.62	0.64
E1	13.10	14.15	0.52	0.56
E2	3.68	5.10	0.14	0.20
E3	1.00	1.90	0.04	0.07
E4	12.38	13.43	0.49	0.53
e	2.54 BSC		0.1 BSC	
e1	5.08 BSC		0.2 BSC	
L	17.31	17.82	0.68	0.70
L1	3.97	4.37	0.16	0.17
L2	2.35	2.65	0.09	0.10
φP	3.51	3.65	0.14	0.14
Q	5.49	6.00	0.22	0.24
S	6.04	6.30	0.24	0.25
T	17.5° REF.			
W	3.5° REF.			
X	4.0° REF.			

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